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Applications of "<u>Embedded - Microcontrollers</u>"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	896B (512 x 14)
Program Memory Type	ОТР
EEPROM Size	-
RAM Size	96 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c620at-20i-so

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### 1.0 GENERAL DESCRIPTION

The PIC16C62X devices are 18 and 20-Pin ROM/EPROM-based members of the versatile PICmicro® family of low cost, high performance, CMOS, fully-static, 8-bit microcontrollers.

All PICmicro microcontrollers employ an advanced RISC architecture. The PIC16C62X devices have enhanced core features, eight-level deep stack, and multiple internal and external interrupt sources. The separate instruction and data buses of the Harvard architecture allow a 14-bit wide instruction word with the separate 8-bit wide data. The two-stage instruction pipeline allows all instructions to execute in a single cycle, except for program branches (which require two cycles). A total of 35 instructions (reduced instruction set) are available. Additionally, a large register set gives some of the architectural innovations used to achieve a very high performance.

PIC16C62X microcontrollers typically achieve a 2:1 code compression and a 4:1 speed improvement over other 8-bit microcontrollers in their class.

The PIC16C620A, PIC16C621A and PIC16CR620A have 96 bytes of RAM. The PIC16C622(A) has 128 bytes of RAM. Each device has 13 I/O pins and an 8-bit timer/counter with an 8-bit programmable prescaler. In addition, the PIC16C62X adds two analog comparators with a programmable on-chip voltage reference module. The comparator module is ideally suited for applications requiring a low cost analog interface (e.g., battery chargers, threshold detectors, white goods controllers, etc).

PIC16C62X devices have special features to reduce external components, thus reducing system cost, enhancing system reliability and reducing power consumption. There are four oscillator options, of which the single pin RC oscillator provides a low cost solution, the LP oscillator minimizes power consumption, XT is a standard crystal, and the HS is for High Speed crystals. The SLEEP (Power-down) mode offers power savings. The user can wake-up the chip from SLEEP through several external and internal interrupts and RESET.

A highly reliable Watchdog Timer with its own on-chip RC oscillator provides protection against software lock- up.

A UV-erasable CERDIP-packaged version is ideal for code development while the cost effective One-Time-Programmable (OTP) version is suitable for production in any volume.

Table 1-1 shows the features of the PIC16C62X midrange microcontroller families.

A simplified block diagram of the PIC16C62X is shown in Figure 3-1.

The PIC16C62X series fits perfectly in applications ranging from battery chargers to low power remote sensors. The EPROM technology makes

customization of application programs (detection levels, pulse generation, timers, etc.) extremely fast and convenient. The small footprint packages make this microcontroller series perfect for all applications with space limitations. Low cost, low power, high performance, ease of use and I/O flexibility make the PIC16C62X very versatile.

### 1.1 Family and Upward Compatibility

Those users familiar with the PIC16C5X family of microcontrollers will realize that this is an enhanced version of the PIC16C5X architecture. Please refer to Appendix A for a detailed list of enhancements. Code written for the PIC16C5X can be easily ported to PIC16C62X family of devices (Appendix B). The PIC16C62X family fills the niche for users wanting to migrate up from the PIC16C5X family and not needing various peripheral features of other members of the PIC16XX mid-range microcontroller family.

### 1.2 Development Support

The PIC16C62X family is supported by a full-featured macro assembler, a software simulator, an in-circuit emulator, a low cost development programmer and a full-featured programmer. Third Party "C" compilers are also available.

FIGURE 4-4: DATA MEMORY MAP FOR THE PIC16C620/621

File Address			File Address			
00h	INDF <sup>(1)</sup>	INDF <sup>(1)</sup>	80h			
01h	TMR0	OPTION	81h			
02h	PCL	PCL	82h			
03h	STATUS	STATUS	83h			
04h	FSR	FSR	84h			
05h	PORTA	TRISA	85h			
06h	PORTB	TRISB	86h			
07h			87h			
08h			88h			
09h			89h			
0Ah	PCLATH	PCLATH	8Ah			
0Bh	INTCON	INTCON	8Bh			
0Ch	PIR1	PIE1	8Ch			
0Dh			8Dh			
0Eh		PCON	8Eh			
0Fh			8Fh			
10h			90h			
11h			91h			
12h			92h			
13h			93h			
14h			94h			
15h			95h			
16h			96h			
17h			97h			
18h			98h			
19h			99h			
1Ah			9Ah			
1Bh			9Bh			
1Ch			9Ch			
1Dh			9Dh			
1Eh			9Eh			
1Fh	CMCON	VRCON	9Fh			
20h	General Purpose		A0h			
6Fh	Register					
70h						
7Fh			FFh			
7111	Bank 0	Bank 1				
Unimplemented data memory locations, read as '0'.						
Note 1: Not a physical register.						

FIGURE 4-5: DATA MEMORY MAP FOR THE PIC16C622

File Address	3		File Address				
00h	INDF <sup>(1)</sup>	INDF <sup>(1)</sup>	80h				
01h	TMR0	OPTION	81h				
02h	PCL	PCL	82h				
03h	STATUS	STATUS	83h				
04h	FSR	FSR	84h				
05h	PORTA	TRISA	85h				
06h	PORTB	TRISB	86h				
07h			87h				
08h			88h				
09h			89h				
0Ah	PCLATH	PCLATH	8Ah				
0Bh	INTCON	INTCON	8Bh				
0Ch	PIR1	PIE1	8Ch				
0Dh			8Dh				
0Eh		PCON	8Eh				
0Fh			8Fh				
10h			90h				
11h			91h				
12h			92h				
13h			93h				
14h			94h				
15h			95h				
16h			96h				
17h			97h				
18h			98h				
19h			99h				
1Ah			9Ah				
1Bh			9Bh				
1Ch			9Ch				
1Dh			9Dh				
1Eh			9Eh				
1Fh	CMCON	VRCON	9Fh				
20h			A0h				
	General	General	7.011				
	Purpose Register	Purpose Register					
	register	rtegister	BFh				
			C0h				
[			_				
7Fh FFh							
Bank 0 Bank 1							
Unimp	Unimplemented data memory locations, read as '0'.						
Note 1:	Not a physical re	egister.					

#### 4.2.2.6 PCON Register

The PCON register contains flag bits to differentiate between a Power-on Reset, an external MCLR Reset, WDT Reset or a Brown-out Reset.

Note: BOR is unknown on Power-on Reset. It must then be set by the user and checked on subsequent RESETS to see if BOR is cleared, indicating a brown-out has occurred. The BOR STATUS bit is a "don't care" and is not necessarily predictable if the brown-out circuit is disabled (by programming BODEN bit in the Configuration word).

### REGISTER 4-6: PCON REGISTER (ADDRESS 8Eh)

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
_	_	_	_	_	_	POR	BOR
bit 7							bit 0

bit 7-2 **Unimplemented:** Read as '0'

bit 1 POR: Power-on Reset STATUS bit

1 = No Power-on Reset occurred

0 = A Power-on Reset occurred (must be set in software after a Power-on Reset occurs)

bit 0 BOR: Brown-out Reset STATUS bit

1 = No Brown-out Reset occurred

0 = A Brown-out Reset occurred (must be set in software after a Brown-out Reset occurs)

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

- n = Value at POR

'1' = Bit is set

'0' = Bit is cleared x = Bit is unknown

#### **5.0 I/O PORTS**

The PIC16C62X have two ports, PORTA and PORTB. Some pins for these I/O ports are multiplexed with an alternate function for the peripheral features on the device. In general, when a peripheral is enabled, that pin may not be used as a general purpose I/O pin.

### 5.1 PORTA and TRISA Registers

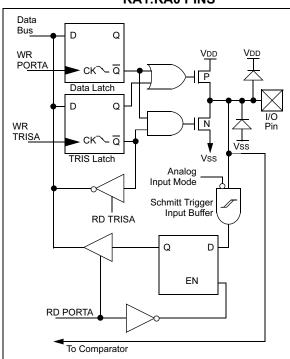
PORTA is a 5-bit wide latch. RA4 is a Schmitt Trigger input and an open drain output. Port RA4 is multiplexed with the T0CKI clock input. All other RA port pins have Schmitt Trigger input levels and full CMOS output drivers. All pins have data direction bits (TRIS registers), which can configure these pins as input or output.

A '1' in the TRISA register puts the corresponding output driver in a Hi-impedance mode. A '0' in the TRISA register puts the contents of the output latch on the selected pin(s).

Reading the PORTA register reads the status of the pins, whereas writing to it will write to the port latch. All write operations are read-modify-write operations. So a write to a port implies that the port pins are first read, then this value is modified and written to the port data latch.

The PORTA pins are multiplexed with comparator and voltage reference functions. The operation of these pins are selected by control bits in the CMCON (comparator control register) register and the VRCON (voltage reference control register) register. When selected as a comparator input, these pins will read as '0's.

FIGURE 5-1: BLOCK DIAGRAM OF RA1:RA0 PINS



On RESET, the TRISA register is set to all inputs. The digital inputs are disabled and the comparator inputs are forced to ground to reduce excess current consumption.

TRISA controls the direction of the RA pins, even when they are being used as comparator inputs. The user must make sure to keep the pins configured as inputs when using them as comparator inputs.

Note:

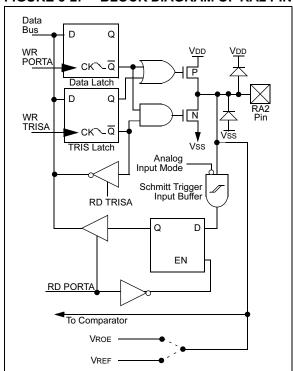
The RA2 pin will also function as the output for the voltage reference. When in this mode, the VREF pin is a very high impedance output and must be buffered prior to any external load. The user must configure TRISA<2> bit as an input and use high impedance loads

In one of the Comparator modes defined by the CMCON register, pins RA3 and RA4 become outputs of the comparators. The TRISA<4:3> bits must be cleared to enable outputs to use this function.

#### **EXAMPLE 5-1: INITIALIZING PORTA**

CLRF	PORTA	;Initialize PORTA by setting ;output data latches
MOVLW	0X07	;Turn comparators off and
MOVWF	CMCON	<pre>;enable pins for I/O ;functions</pre>
BSF	STATUS, RPO	;Select Bank1
MOVLW	0x1F	; Value used to initialize
		;data direction
MOVWF	TRISA	;Set RA<4:0> as inputs
		;TRISA<7:5> are always
		;read as '0'.

#### FIGURE 5-2: BLOCK DIAGRAM OF RA2 PIN



### 6.2 Using Timer0 with External Clock

When an external clock input is used for Timer0, it must meet certain requirements. The external clock requirement is due to internal phase clock (Tosc) synchronization. Also, there is a delay in the actual incrementing of Timer0 after synchronization.

### 6.2.1 EXTERNAL CLOCK SYNCHRONIZATION

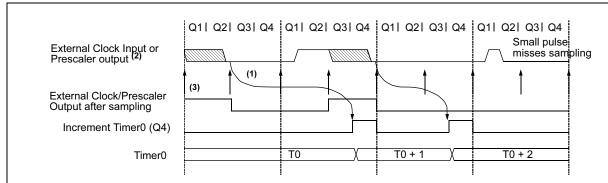
When no prescaler is used, the external clock input is the same as the prescaler output. The synchronization of T0CKI with the internal phase clocks is accomplished by sampling the prescaler output on the Q2 and Q4 cycles of the internal phase clocks (Figure 6-5). Therefore, it is necessary for T0CKI to be high for at least 2Tosc (and a small RC delay of 20 ns) and low for at least 2Tosc (and a small RC delay of 20 ns). Refer to the electrical specification of the desired device.

When a prescaler is used, the external clock input is divided by the asynchronous ripple-counter type prescaler, so that the prescaler output is symmetrical. For the external clock to meet the sampling requirement, the ripple-counter must be taken into account. Therefore, it is necessary for T0CKI to have a period of at least 4Tosc (and a small RC delay of 40 ns) divided by the prescaler value. The only requirement on T0CKI high and low time is that they do not violate the minimum pulse width requirement of 10 ns. Refer to parameters 40, 41 and 42 in the electrical specification of the desired device.

#### 6.2.2 TIMERO INCREMENT DELAY

Since the prescaler output is synchronized with the internal clocks, there is a small delay from the time the external clock edge occurs to the time the TMR0 is actually incremented. Figure 6-5 shows the delay from the external clock edge to the timer incrementing.

FIGURE 6-5: TIMERO TIMING WITH EXTERNAL CLOCK



- Note 1: Delay from clock input change to Timer0 increment is 3Tosc to 7Tosc. (Duration of Q = Tosc).

  Therefore, the error in measuring the interval between two edges on Timer0 input = ±4Tosc max.
  - 2: External clock if no prescaler selected, Prescaler output otherwise.
  - 3: The arrows indicate the points in time where sampling occurs.

### 6.3.1 SWITCHING PRESCALER ASSIGNMENT

The prescaler assignment is fully under software control (i.e., it can be changed "on-the-fly" during program execution). To avoid an unintended device RESET, the following instruction sequence (Example 6-1) must be executed when changing the prescaler assignment from Timer0 to WDT.)

### EXAMPLE 6-1: CHANGING PRESCALER (TIMER0→WDT)

	,	
1.BCF	STATUS, RPO	;Skip if already in ;Bank 0
2.CLRWDT		;Clear WDT
3.CLRF	TMR0	;Clear TMR0 & Prescaler
4.BSF	STATUS, RPO	;Bank 1
5.MOVLW	'00101111'b;	;These 3 lines (5, 6, 7)
6.MOVWF	OPTION	<pre>;are required only if ;desired PS&lt;2:0&gt; are</pre>
7.CLRWDT		;000 or 001
8.MOVLW	'00101xxx'b	;Set Postscaler to
9.MOVWF	OPTION	;desired WDT rate
10.BCF	STATUS, RP0	;Return to Bank 0

To change prescaler from the WDT to the TMR0 module, use the sequence shown in Example 6-2. This precaution must be taken even if the WDT is disabled.

### EXAMPLE 6-2: CHANGING PRESCALER (WDT→TIMER0)

CLRWDT		;Clear WDT and ;prescaler
BSF	STATUS, RPO	-
MOVLW	b'xxxx0xxx'	;Select TMR0, new ;prescale value and ;clock source
MOVWF	OPTION_REG	
BCF	STATUS, RPO	

#### TABLE 6-1: REGISTERS ASSOCIATED WITH TIMERO

INDLE	ABLE VII. REGISTERS ASSOCIATED WITH THILLIA										
Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR	Value on All Other RESETS
01h	TMR0	Timer0	module reg	ister						xxxx xxxx	uuuu uuuu
0Bh/8Bh	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
81h	OPTION	RBPU	INTEDG	TOCS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
85h	TRISA	_	_	_	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	1 1111	1 1111

Legend: — = Unimplemented locations, read as '0', u = unchanged, x = unknown

Note: Shaded bits are not used by TMR0 module.

TABLE 10-2: PIC16C62X INSTRUCTION SET

Mnemonic,		Description			14-Bit	Opcode	)	Status	Notes
Operands				MSb			LSb	Affected	
BYTE-ORIE	NTED F	FILE REGISTER OPERATIONS							
ADDWF	f, d	Add W and f	1	00	0111	dfff	ffff	C,DC,Z	1,2
ANDWF	f, d	AND W with f	1	00	0101	dfff	ffff	Z	1,2
CLRF	f	Clear f	1	00	0001	lfff	ffff	Z	2
CLRW	-	Clear W	1	00	0001	0000	0011	Z	
COMF	f, d	Complement f	1	00	1001	dfff	ffff	Z	1,2
DECF	f, d	Decrement f	1	00	0011	dfff	ffff	Z	1,2
DECFSZ	f, d	Decrement f, Skip if 0	1(2)	00	1011	dfff	ffff		1,2,3
INCF	f, d	Increment f	1	00	1010	dfff	ffff	Z	1,2
INCFSZ	f, d	Increment f, Skip if 0	1(2)	00	1111	dfff	ffff		1,2,3
IORWF	f, d	Inclusive OR W with f	1	00	0100	dfff	ffff	Z	1,2
MOVF	f, d	Move f	1	00	1000	dfff	ffff	Z	1,2
MOVWF	f	Move W to f	1	00	0000	lfff	ffff		
NOP	-	No Operation	1	00	0000	0xx0	0000		
RLF	f, d	Rotate Left f through Carry	1	00	1101	dfff	ffff	С	1,2
RRF	f, d	Rotate Right f through Carry	1	00	1100	dfff	ffff	С	1,2
SUBWF	f, d	Subtract W from f	1	00	0010	dfff	ffff	C,DC,Z	1,2
SWAPF	f, d	Swap nibbles in f	1	00	1110	dfff	ffff		1,2
XORWF	f, d	Exclusive OR W with f	1	00	0110	dfff	ffff	Z	1,2
BIT-ORIENT	ED FIL	E REGISTER OPERATIONS							
BCF	f, b	Bit Clear f	1	01	00bb	bfff	ffff		1,2
BSF	f, b	Bit Set f	1	01	01bb	bfff	ffff		1,2
BTFSC	f, b	Bit Test f, Skip if Clear	1 (2)	01	10bb	bfff	ffff		3
BTFSS	f, b	Bit Test f, Skip if Set	1 (2)	01	11bb	bfff	ffff		3
LITERAL AN	ID CO	NTROL OPERATIONS							
ADDLW	k	Add literal and W	1	11	111x	kkkk	kkkk	C,DC,Z	
ANDLW	k	AND literal with W	1	11	1001	kkkk	kkkk	Z	
CALL	k	Call subroutine	2	10	0kkk	kkkk	kkkk		
CLRWDT	-	Clear Watchdog Timer	1	00	0000	0110	0100	TO,PD	
GOTO	k	Go to address	2	10	1kkk	kkkk	kkkk		
IORLW	k	Inclusive OR literal with W	1	11	1000	kkkk	kkkk	Z	
MOVLW	k	Move literal to W	1	11	00xx	kkkk	kkkk		
RETFIE	-	Return from interrupt	2	00	0000	0000	1001		
RETLW	k	Return with literal in W	2	11	01xx	kkkk	kkkk		
RETURN	-	Return from Subroutine	2	00	0000	0000	1000		
SLEEP	-	Go into Standby mode	1	00	0000	0110	0011	TO,PD	
SUBLW	k	Subtract W from literal	1	11	110x	kkkk	kkkk	C,DC,Z	
XORLW	k	Exclusive OR literal with W	1	11	1010	kkkk	kkkk	Z	

Note 1: When an I/O register is modified as a function of itself (e.g., MOVF PORTB, 1), the value used will be that value present on the pins themselves. For example, if the data latch is '1' for a pin configured as input and is driven low by an external device, the data will be written back with a '0'.

<sup>2:</sup> If this instruction is executed on the TMR0 register (and, where applicable, d = 1), the prescaler will be cleared if assigned to the Timer0 Module.

<sup>3:</sup> If Program Counter (PC) is modified or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a NOP.

### 10.1 Instruction Descriptions

ADDLW	Add Literal and W						
Syntax:	[label] ADDLW k						
Operands:	$0 \leq k \leq 255$						
Operation:	(W) + k –	→ (W)					
Status Affected:	C, DC, Z						
Encoding:	11	111x	kkkk	kkkk			
Description:	The contents of the W register are added to the eight bit literal 'k' and the result is placed in the W register.						
Words:	1						
Cycles:	1						
Example	ADDLW	0x15					
	After Inst	W =	0x10 0x25				

ADDWF	Add W a	nd f					
Syntax:	[ label ] ADDWF f,d						
Operands:	$0 \le f \le 127$ $d \in [0,1]$						
Operation:	(W) + (f)	→ (dest)	)				
Status Affected:	C, DC, Z						
Encoding:	00	0111	dfff	ffff			
Description:	Add the contents of the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.						
Words:	1						
Cycles:	1						
Example	ADDWF	FSR,	0				
	After Inst	W = FSR =	0x17 0xC2 0xD9 0xC2				

ANDLW	AND Literal with W								
Syntax:	[ label ] ANDLW k								
Operands:	$0 \leq k \leq 255$								
Operation:	(W) .AND	$0. (k) \rightarrow 0$	(W)						
Status Affected:	Z								
Encoding:	11	1001	kkkk	kkkk					
Description:	The contents of W register are AND'ed with the eight bit literal 'k'. The result is placed in the W register.								
Words:	1								
Cycles:	1								
Example	ANDLW	0x5F							
	After Inst	W =	0xA3 0x03						

ANDWF	AND W with f									
Syntax:	[ label ] ANDWF f,d									
Operands:	$0 \le f \le 127$									
	$d \in [0,1]$									
Operation:	(W) .AND. (f) $\rightarrow$ (dest)									
Status Affected:	Z									
Encoding:	00 0101 dfff ffff									
Description:	AND the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.									
Words:	1									
Cycles:	1									
Example	ANDWF FSR, 1									
	Before Instruction									
	W = 0x17									
	FSR = 0xC2									
	After Instruction									
	W = 0x17 FSR = 0x02									
	FSR = 0x02									

SWAPF	Swap Nibbles in f								
Syntax:	[ label ]	SWAPF	f,d						
Operands:	$0 \le f \le 127$ d $\in [0,1]$								
Operation:	(f<3:0>) - (f<7:4>) -	•	, ,						
Status Affected:	None								
Encoding:	00	1110	dfff	ffff					
Description:	The upper and lower nibbles of register 'f' are exchanged. If 'd' is 0, the result is placed in W register. If 'd' is 1, the result is placed in register 'f'.								
Words:	1								
Cycles:	1								
Example	SWAPF	REG,	0						
	Before In	struction							
		REG1	= (	0xA5					
	After Instruction								
		REG1 W		0xA5 0x5A					

TRIS	Load TRIS Register								
Syntax:	[ label ]	TRIS	f						
Operands:	$5 \leq f \leq 7$								
Operation:	$(W) \rightarrow TF$	RIS regis	ter f;						
Status Affected:	None								
Encoding:	00	0000	0110	Offf					
Description:	The instruction is supported for code compatibility with the PIC16C5X products. Since TRIS registers are readable and writable, the user can directly address them.								
Words:	1								
Cycles:	1								
Example									
	To maintain upward compatibility with future PICmicro <sup>®</sup> products, do not use this instruction.								

XORLW	Exclusive OR Literal with W							
Syntax:	[ label XORLW k ]							
Operands:	$0 \leq k \leq 255$							
Operation:	(W) .XOR. $k \rightarrow (W)$							
Status Affected:	Z							
Encoding:	11 1010 kkkk kkkk							
Description: Words:	The contents of the W register are XOR'ed with the eight bit literal 'k'. The result is placed in the W register.							
Cycles:	1							
Example:	XORLW 0xAF							
	Before Instruction							
	W = 0xB5							
	After Instruction							
	W = 0x1A							
XORWE	Exclusive OR W with f							

XORWF	Exclusive OR W with f									
Syntax:	[ label ] XORWF f,d									
Operands:	$0 \le f \le 127$ $d \in [0,1]$									
Operation:	(W) .XOF	$R. (f) \rightarrow (e$	dest)							
Status Affected:	Z									
Encoding:	00	0110	dff	f	ffff					
Description:	Exclusive OR the contents of the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.									
Words:	1									
Cycles:	1									
Example	XORWF	REG	1							
	Before In	struction								
	0xA 0xE	••								
	After Inst	ruction								
	REG = 0x1A W = 0xB5									

## 11.9 MPLAB ICE 2000 High Performance Universal In-Circuit Emulator

The MPLAB ICE 2000 universal in-circuit emulator is intended to provide the product development engineer with a complete microcontroller design tool set for PICmicro microcontrollers. Software control of the MPLAB ICE 2000 in-circuit emulator is advanced by the MPLAB Integrated Development Environment, which allows editing, building, downloading and source debugging from a single environment.

The MPLAB ICE 2000 is a full-featured emulator system with enhanced trace, trigger and data monitoring features. Interchangeable processor modules allow the system to be easily reconfigured for emulation of different processors. The universal architecture of the MPLAB ICE in-circuit emulator allows expansion to support new PICmicro microcontrollers.

The MPLAB ICE 2000 in-circuit emulator system has been designed as a real-time emulation system with advanced features that are typically found on more expensive development tools. The PC platform and Microsoft<sup>®</sup> Windows 32-bit operating system were chosen to best make these features available in a simple, unified application.

# 11.10 MPLAB ICE 4000 High Performance Universal In-Circuit Emulator

The MPLAB ICE 4000 universal in-circuit emulator is intended to provide the product development engineer with a complete microcontroller design tool set for highend PICmicro microcontrollers. Software control of the MPLAB ICE in-circuit emulator is provided by the MPLAB Integrated Development Environment, which allows editing, building, downloading and source debugging from a single environment.

The MPLAB ICD 4000 is a premium emulator system, providing the features of MPLAB ICE 2000, but with increased emulation memory and high speed performance for dsPIC30F and PIC18XXXX devices. Its advanced emulator features include complex triggering and timing, up to 2 Mb of emulation memory, and the ability to view variables in real-time.

The MPLAB ICE 4000 in-circuit emulator system has been designed as a real-time emulation system with advanced features that are typically found on more expensive development tools. The PC platform and Microsoft Windows 32-bit operating system were chosen to best make these features available in a simple, unified application.

### 11.11 MPLAB ICD 2 In-Circuit Debugger

Microchip's In-Circuit Debugger, MPLAB ICD 2, is a powerful, low cost, run-time development tool, connecting to the host PC via an RS-232 or high speed USB interface. This tool is based on the FLASH PICmicro MCUs and can be used to develop for these and other PICmicro microcontrollers. The MPLAB ICD 2 utilizes the in-circuit debugging capability built into the FLASH devices. This feature, along with Microchip's In-Circuit Serial Programming™ (ICSP™) protocol, offers cost effective in-circuit FLASH debugging from the graphical user interface of the MPLAB Integrated Development Environment. This enables a designer to develop and debug source code by setting breakpoints, single-stepping and watching variables, CPU status and peripheral registers. Running at full speed enables testing hardware and applications in real-time. MPLAB ICD 2 also serves as a development programmer for selected PICmicro devices.

### 11.12 PRO MATE II Universal Device Programmer

The PRO MATE II is a universal, CE compliant device programmer with programmable voltage verification at VDDMIN and VDDMAX for maximum reliability. It features an LCD display for instructions and error messages and a modular detachable socket assembly to support various package types. In Stand-Alone mode, the PRO MATE II device programmer can read, verify, and program PICmicro devices without a PC connection. It can also set code protection in this mode.

## 11.13 PICSTART Plus Development Programmer

The PICSTART Plus development programmer is an easy-to-use, low cost, prototype programmer. It connects to the PC via a COM (RS-232) port. MPLAB Integrated Development Environment software makes using the programmer simple and efficient. The PICSTART Plus development programmer supports most PICmicro devices up to 40 pins. Larger pin count devices, such as the PIC16C92X and PIC17C76X, may be supported with an adapter socket. The PICSTART Plus development programmer is CE compliant.

# 12.1 DC Characteristics: PIC16C62X-04 (Commercial, Industrial, Extended) PIC16C62X-20 (Commercial, Industrial, Extended) PIC16LC62X-04 (Commercial, Industrial, Extended) (CONT.)

PIC16C			Standard Operating Conditions (unless otherwise stated)  Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended  Standard Operating Conditions (unless otherwise stated)  Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended						
	ı					V <sub>DD</sub> ran	ge is the PIC16C62X range.		
Param . No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions		
D022 D022A D023 D023A D022 D022A D023 D023A	ΔIWDT  ΔIBOR ΔICOM P  ΔIVREF ΔIWDT ΔIBOR ΔICOM P  ΔIVREF	WDT Current <sup>(5)</sup> Brown-out Reset Current <sup>(5)</sup> Comparator Current for each Comparator <sup>(5)</sup> VREF Current <sup>(5)</sup> WDT Current <sup>(5)</sup> Brown-out Reset Current <sup>(5)</sup> Comparator Current for each Comparator <sup>(5)</sup> VREF Current <sup>(5)</sup>		6.0 350 — 6.0 350 —	20 25 425 100 300 15 425 100 300	ДА ДА ДА ДА ДА ДА ДА ДА	VDD=4.0V (125°C) BOD enabled, VDD = 5.0V VDD = 4.0V  VDD = 4.0V  VDD=3.0V BOD enabled, VDD = 5.0V VDD = 3.0V VDD = 3.0V		
1A	Fosc	LP Oscillator Operating Frequency RC Oscillator Operating Frequency XT Oscillator Operating Frequency HS Oscillator Operating Frequency	0 0 0 0		200 4 4 20	kHz MHz MHz MHz	All temperatures All temperatures All temperatures All temperatures		
1A	Fosc	LP Oscillator Operating Frequency RC Oscillator Operating Frequency XT Oscillator Operating Frequency HS Oscillator Operating Frequency	0 0 0 0	_ _ _ _	200 4 4 20	kHz MHz MHz MHz	All temperatures All temperatures All temperatures All temperatures		

- \* These parameters are characterized but not tested.
- † Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.
- Note 1: This is the limit to which VDD can be lowered without losing RAM data.
  - 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in Active Operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD,

MCLR = VDD; WDT enabled/disabled as specified.

- 3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or Vss.
- **4:** For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula: Ir = VDD/2REXT (mA) with REXT in kΩ.
- 5: The  $\Delta$  current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

12.2 DC Characteristics: PIC16C62XA-04 (Commercial, Industrial, Extended)
PIC16C62XA-20 (Commercial, Industrial, Extended)
PIC16LC62XA-04 (Commercial, Industrial, Extended)

PIC16C62XA											
Param. No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions				
D001	VDD	Supply Voltage	3.0	_	5.5	V	See Figures 12-1, 12-2, 12-3, 12-4, and 12-5				
D001	VDD	Supply Voltage	2.5	_	5.5	V	See Figures 12-1, 12-2, 12-3, 12-4, and 12-5				
D002	VDR	RAM Data Retention Voltage <sup>(1)</sup>	_	1.5*	_	V	Device in SLEEP mode				
D002	VDR	RAM Data Retention Voltage <sup>(1)</sup>	_	1.5*	_	V	Device in SLEEP mode				
D003	VPOR	VDD start voltage to ensure Power-on Reset	_	Vss	_	٧	See section on Power-on Reset for details				
D003	VPOR	VDD start voltage to ensure Power-on Reset	_	Vss	_	٧	See section on Power-on Reset for details				
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	_	_	V/ms	See section on Power-on Reset for details				
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	_	_	V/ms	See section on Power-on Reset for details				
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared				
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared				

- \* These parameters are characterized but not tested.
- † Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.
- Note 1: This is the limit to which VDD can be lowered without losing RAM data.
  - 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in Active Operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD,

MCLR = VDD; WDT enabled/disabled as specified.

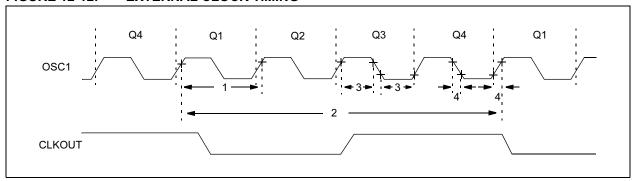
- 3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or Vss.
- **4:** For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula: Ir = VDD/2REXT (mA) with REXT in kΩ.
- 5: The  $\Delta$  current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.
- 6: Commercial temperature range only.

PIC16CR62XA-04 Operating Conditions (unless otherwise stated)  Operating temperature $-40^{\circ}\text{C} \le \text{TA} \le +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \le \text{TA} \le +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \le \text{TA} \le +125^{\circ}\text{C}$ for extended						
PIC16LCR62XA-04	Standard Operating Conditions (unless otherwise stated)  Operating temperature $-40^{\circ}\text{C} \leq \text{TA} \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq \text{TA} \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq \text{TA} \leq +125^{\circ}\text{C}$ for extended					
Param. Sym Characteristic No.	Min Typ† Max Units Conditions					

- \* These parameters are characterized but not tested.
- † Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.
- Note 1: This is the limit to which VDD can be lowered without losing RAM data.
  - 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
    - The test conditions for all IDD measurements in Active Operation mode are:
    - $\underline{\mathsf{OSC1}}$  = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD,
    - MCLR = VDD; WDT enabled/disabled as specified.
  - 3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or Vss.
  - **4:** For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula: Ir = VDD/2REXT (mA) with REXT in kΩ.
  - 5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.
  - 6: Commercial temperature range only.

### 12.9 Timing Diagrams and Specifications

FIGURE 12-12: EXTERNAL CLOCK TIMING



**TABLE 12-3: EXTERNAL CLOCK TIMING REQUIREMENTS** 

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
1A	Fosc	External CLKIN Frequency <sup>(1)</sup>	DC	_	4	MHz	XT and RC Osc mode, VDD=5.0V
			DC	_	20	MHz	HS Osc mode
			DC	_	200	kHz	LP Osc mode
		Oscillator Frequency <sup>(1)</sup>	DC	_	4	MHz	RC Osc mode, VDD=5.0V
			0.1	_	4	MHz	XT Osc mode
			1	_	20	MHz	HS Osc mode
			DC	_	200	kHz	LP Osc mode
1	Tosc	External CLKIN Period <sup>(1)</sup>	250	_	_	ns	XT and RC Osc mode
			50	_	_	ns	HS Osc mode
			5	_	_	μS	LP Osc mode
		Oscillator Period <sup>(1)</sup>	250	_	_	ns	RC Osc mode
			250	_	10,000	ns	XT Osc mode
			50	_	1,000	ns	HS Osc mode
			5	_	_	μS	LP Osc mode
2	TCY	Instruction Cycle Time <sup>(1)</sup>	1.0	Fosc/4	DC	μS	Tcys=Fosc/4
3*	TosL,	External Clock in (OSC1) High or	100*	_	_	ns	XT oscillator, Tosc L/H duty cycle
	TosH	Low Time	2*	_	_	μS	LP oscillator, Tosc L/H duty cycle
			20*	_	_	ns	HS oscillator, Tosc L/H duty cycle
4*	TosR,	External Clock in (OSC1) Rise or	25*	_	_	ns	XT oscillator
	TosF	Fall Time	50*	_	_	ns	LP oscillator
			15*	_	_	ns	HS oscillator

<sup>2: \*</sup> These parameters are characterized but not tested.

<sup>3: †</sup> Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1 pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

FIGURE 12-14: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING

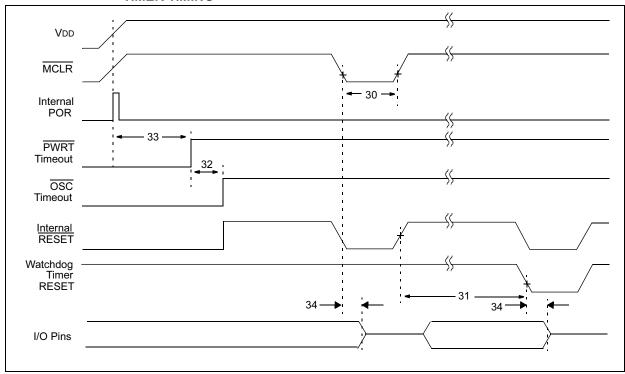


FIGURE 12-15: BROWN-OUT RESET TIMING

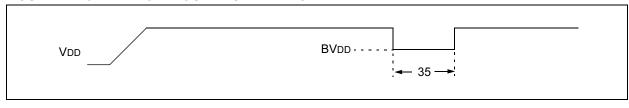


TABLE 12-5: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
30	TmcL	MCLR Pulse Width (low)	2000	_	_	ns	-40° to +85°C
31	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7*	18	33*	ms	VDD = 5.0V, -40° to +85°C
32	Tost	Oscillation Start-up Timer Period	_	1024 Tosc	_	_	Tosc = OSC1 period
33	Tpwrt	Power-up Timer Period	28*	72	132*	ms	V <sub>DD</sub> = 5.0V, -40° to +85°C
34	Tıoz	I/O hi-impedance from MCLR low		_	2.0	μS	
35	TBOR	Brown-out Reset Pulse Width	100*	_	_	μS	$3.7V \le VDD \le 4.3V$

<sup>\*</sup> These parameters are characterized but not tested.

<sup>†</sup> Data in "Typ" column is at 5.0V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 12-16: TIMER0 CLOCK TIMING

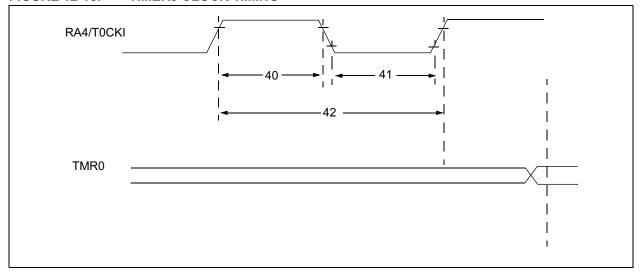


TABLE 12-6: TIMERO CLOCK REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Тур†	Max	Units	Conditions
40	Tt0H	T0CKI High Pulse Width	No Prescaler	0.5 Tcy + 20*	_	_	ns	
			With Prescaler	10*	_	_	ns	
41	Tt0L	T0CKI Low Pulse Width	No Prescaler	0.5 Tcy + 20*	_	_	ns	
			With Prescaler	10*	_	_	ns	
42	Tt0P	T0CKI Period		TCY + 40* N	_	_	ns	N = prescale value (1, 2, 4,, 256)

These parameters are characterized but not tested.

<sup>†</sup> Data in "Typ" column is at 5.0V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.

### 13.0 DEVICE CHARACTERIZATION INFORMATION

The graphs and tables provided in this section are for design guidance and are not tested. In some graphs or tables, the data presented is outside specified operating range (e.g., outside specified VDD range). This is for information only and devices will operate properly only within the specified range.

The data presented in this section is a statistical summary of data collected on units from different lots over a period of time. "Typical" represents the mean of the distribution, while "max" or "min" represents (mean +  $3\sigma$ ) and (mean –  $3\sigma$ ) respectively, where  $\sigma$  is standard deviation.

FIGURE 13-1: IDD VS. FREQUENCY (XT MODE, VDD = 5.5V)

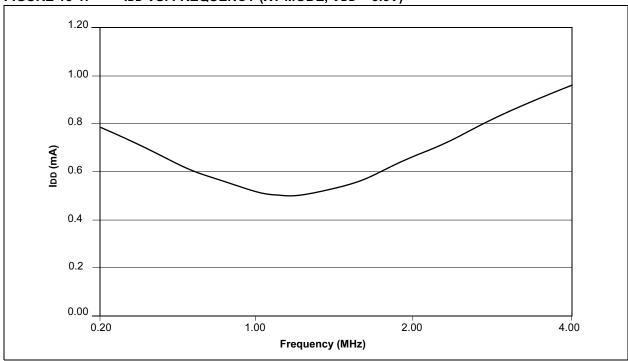
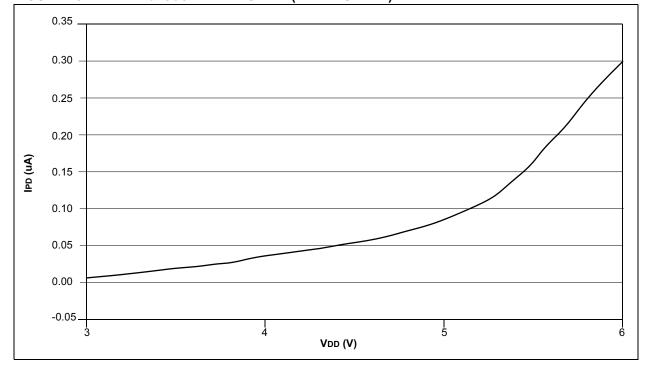
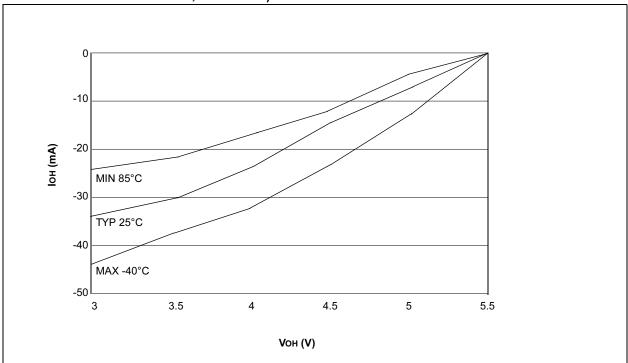


FIGURE 13-2: PIC16C622A IPD VS. VDD (WDT DISABLE)







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	4.4	In-Circuit Emulator	77
General purpose Register File		MPLAB Integrated Development Environment Software	
OOTO ITISTRUCTION	01	MPLINK Object Linker/MPLIB Object Librarian	